TOSHIBA PHOTO-INTERRUPTER INFRARED LED + PHOTODARLINGTON TRANSISTOR

TLP507A

HIGH-POWER AMPLIFIER APPLICATIONS

AUTOMATIC CONTROL UNITS

POSITION AND ROTATIONAL SPEED SENSORS

The TLP507A photo-interrupter features a high current transfer ratio (IC / IF).

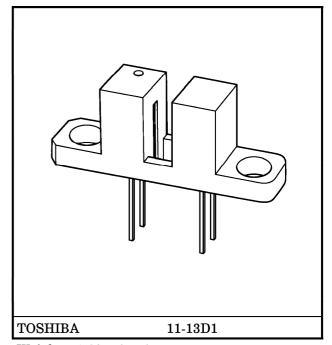
• Gap : 3 mm

• Resolution : Slit width = 0.5 mm

• High current transfer ratio: $I_C/I_F = 30\%$ (min)

• Dark current : $I_D = 0.25 \,\mu\text{A}$ (max)

• Package material : Polycarbonate

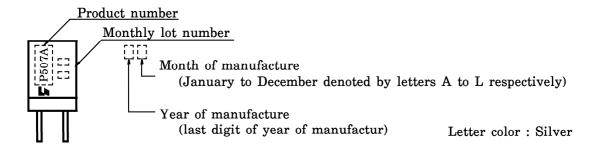


Weight: 0.83 g (typ.)

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
LED	Forward Current	$I_{\mathbf{F}}$	50	mA	
	Forward Current Derating	4In /°C	-0.33	mA/°C	
	$(Ta > 25^{\circ}C)$	$\Delta I_{\mathbf{F}}/^{\circ}\mathbf{C}$	-0.55	IIIA/ C	
	Reverse Voltage	v_{R}	5	V	
R	Collector-Emitter Voltage	v_{CEO}	30	V	
DETECTO	Emitter-Collector Voltage	v_{ECO}	5	V	
	Collector Power Dissipation	$P_{\mathbf{C}}$	75	mW	
	Collector Power Dissipation	4Ba /°C	_1	mW/°C	
	Derating (Ta > 25 °C)	$\Delta P_{C} / {^{\circ}C}$	-1	III VV / C	
	Collector Current	$I_{\mathbf{C}}$	50	mA	
Or	erating Temperature Range	${ m T_{opr}}$	-25~85	$^{\circ}\mathrm{C}$	
Ste	orage Temperature Range	$\mathrm{T_{stg}}$	-30~100	$^{\circ}\mathrm{C}$	

MARKINGS



OPTICAL AND ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	Min	Тур.	Max	UNIT
LED	Forward Voltage	$ m V_{ m F}$	$I_{ m F}=10{ m mA}$	1.00	1.15	1.30	V
	Reverse Current	$I_{ m R}$	$V_{R} = 5 V$	_	_	10	μ A
	Peak Emission Wavelength	$\lambda \mathbf{P}$	$ m I_F = 10~mA$	_	940		nm
DETECTOR	Dark Current	I _D (I _{CEO})	$V_{ m CE} = 16 m V, I_{ m F} = 0$	1	1	0.25	μ A
	Peak Sensitivity Wavelength	$\lambda_{\mathbf{P}}$	_	1	800	1	nm
ED,	Current Transfer Ratio	$I_{\mathbf{C}}/I_{\mathbf{F}}$	$V_{ m CE} = 2 m V, I_{ m F} = 10 mA$	30		440	%
COUPLED	Rise Time	$t_{\mathbf{r}}$	$V_{\mathrm{CC}} = 5 \mathrm{V}, \; \mathrm{I_{\mathrm{C}}} = 10 \mathrm{mA}, \ \mathrm{R_{\mathrm{L}}} = 100 \Omega$	_	200	_	
	Fall Time	t_f			200		μ s

PRECAUTIONS

The following points must be borne in mind.

1. Soldering temperature: 260°C max

Soldering time: 5 s max

(Soldering must be performed 1.5 mm under the package body.)

- 2. Clean only the soldered part of the leads. Do not immerse the entire package in the cleaning solvent.
- 3. Mount the device on a level surface.
- 4. Screws should be tightened to a clamping torque of 0.59 N·m.
- 5. The package is made of polycarbonate. Polycarbonate is usually stable with acid, alcohol and aliphatic hydrocarbons, however, with petrochemicals (such as benzene, toluene and acetone), alkalis, aromatic hydrocarbons, or chloric hydrocarbons, polycarbonate may crack, swell or melt. Please take this into account when chosing a packaging material by referring to the table below.

<Chemicals which should not be used with polycarbonate>

	PHENOMENON	CHEMICALS	
A	Staining and slight deterioration	Nitric acid (diluted), hydrogen peroxide, chlorine	
В	Cracking, crazed or swelling	 Acetic acid (70% or more) Gasoline Methyl ethyl ketone, ethyl acetate, butyl acetate Ethyl methacrylate, ethyl ether, MEK Acetone, m-amino alcohol, carbon tetrachloride Carbon disulfide, trichloroethylene, cresol Thinners, oil of turpentine Triethanolamine, TCP, TBP 	
С	Melting { }: Used as solvent	 Concentrated sulfuric acid Benzene Styrene, acrylonitrile, vinyl acetate Ethylenediamine, diethylenediamine Chloroform, methyl chloride, tetrachloromethane, dioxane, 1, 2-dichloroethane 	
D	Decomposition	Ammonia water Other alkalis	

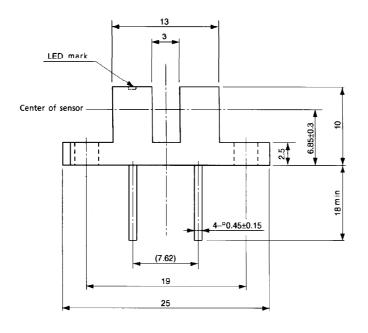
6. Conversion efficiency falls over time due to the current which flows in the infrared LED. When designing a circuit, take into account this change in conversion efficiency over time. The ratio of fluctuation in conversion efficiency to fluctuation in infrared LED optical output is 1:1.

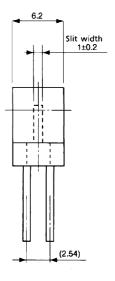
$$\frac{I_{C}/I_{F}(t)}{I_{C}/I_{F}(0)} = \frac{P_{O}(t)}{P_{O}(0)}$$

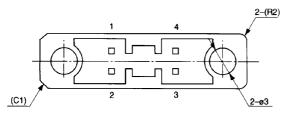
PACKAGE DIMENSIONS

11-13D1

Unit: mm



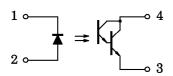




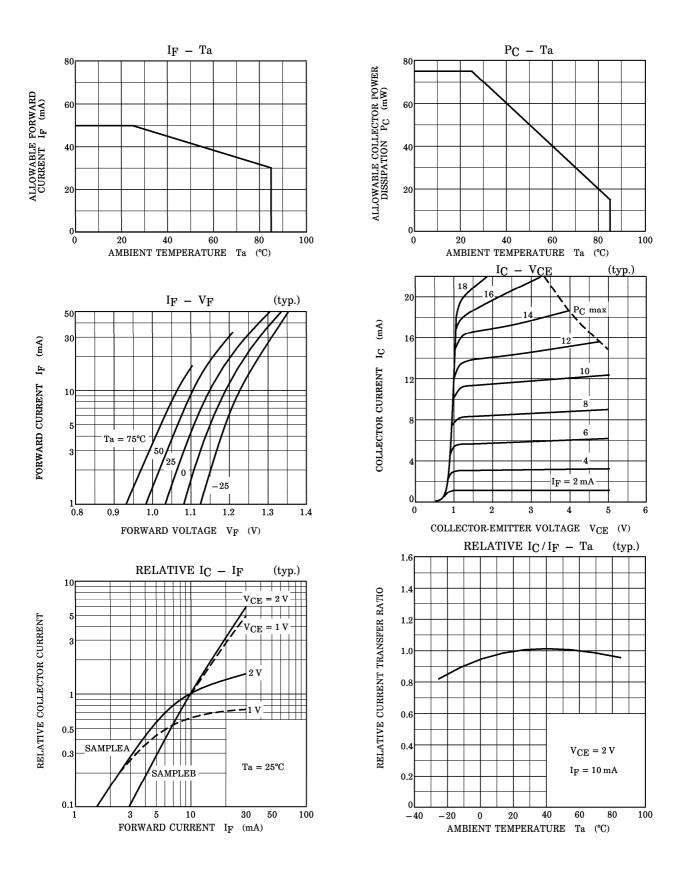
Tolerance unless otherwise specified : ± 0.25 () : Reference value

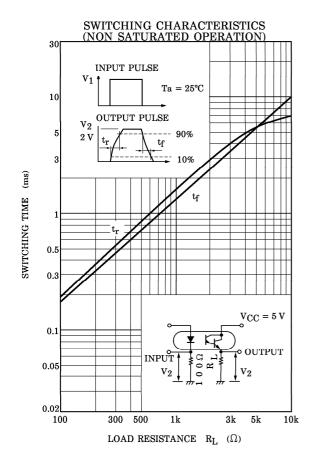
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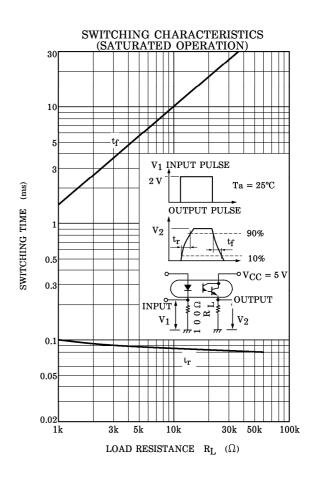
PIN CONNECTION

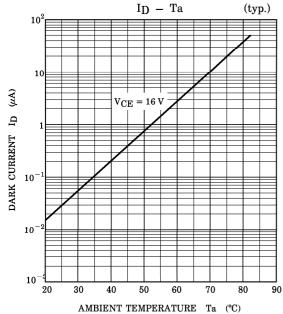


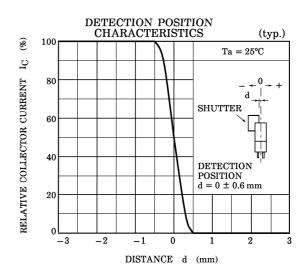
- 1. Cathode
- 2. Anode
- 3. Emitter
- 4. Collector





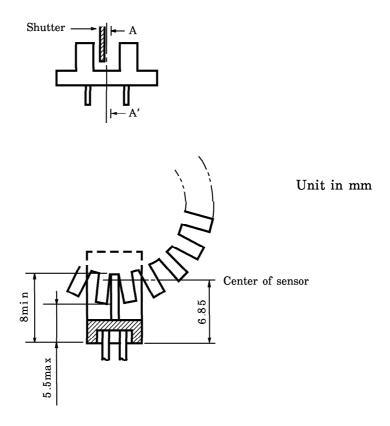






RELATIVE POSITIONING OF SHUTTER AND DEVICE

For normal operation position the shutter and the device as shown in the figure below. By considering the device's detection direction characteristic and switching time, determine the shutter slit width and pitch.



Cross section between A and A'

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